74ALVC541-Q100

Octal buffer/line driver; 3-state

Rev. 1 — 19 May 2014 Product data sheet

1. General description

The 74ALVC541-Q100 is an octal non-inverting buffer/line driver with 3-state bus compatible outputs. The output enable inputs $\overline{OE}0$ and $\overline{OE}1$, control the 3-state outputs. A HIGH on $\overline{OE}n$ causes the outputs to assume a high-impedance OFF-state.

This product has been qualified to the Automotive Electronics Council (AEC) standard Q100 (Grade 3) and is suitable for use in automotive applications.

2. Features and benefits

- Automotive product qualification in accordance with AEC-Q100 (Grade 3)
  - Specified from −40 °C to +85 °C
- Wide supply voltage range from 1.65 V to 3.6 V
- 3.6 V tolerant inputs/outputs
- CMOS LOW power consumption
- Direct interface with TTL levels (2.7 V to 3.6 V)
- Power-down mode
- Latch-up performance exceeds 250 mA
- Complies with JEDEC standard:
  - JESD8-7 (1.65 V to 1.95 V)
  - JESD8-5 (2.3 V to 2.5 V)
  - JESD8B/JESD36 (2.7 V to 3.6 V)
- ESD protection:
  - MIL-STD-883, method 3015 exceeds 2000 V
  - HBM JESD22-A114F exceeds 2000 V
  - MM JESD22-A115-A exceeds 200 V (C = 200 pF, R = 0 Ω)

3. Ordering information

Table 1. Ordering information

Type number	Package			
	Temperature range	Name	Description	Version
74ALVC541D-Q100	–40 °C to +85 °C	SO20	plastic small outline package; 20 leads; body width 7.5 mm	SOT163-1
74ALVC541PW-Q100	–40 °C to +85 °C	TSSOP20	plastic thin shrink small outline package; 20 leads; body width 4.4 mm	SOT360-1
74ALVC541BQ-Q100	–40 °C to +85 °C	DHVQFN20	plastic dual-in-line compatible thermal enhanced very thin quad flat package no leads; 20 terminals; body 2.5 × 4.5 × 0.85 mm	SOT764-1

4. Functional diagram

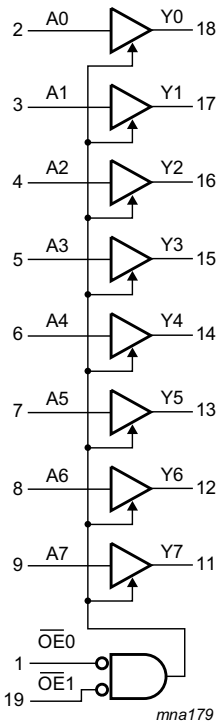


Fig 1. Logic symbol

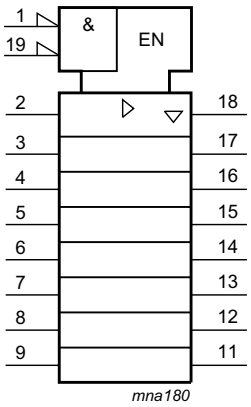


Fig 2. IEC logic symbol

5. Pinning information

5.1 Pinning

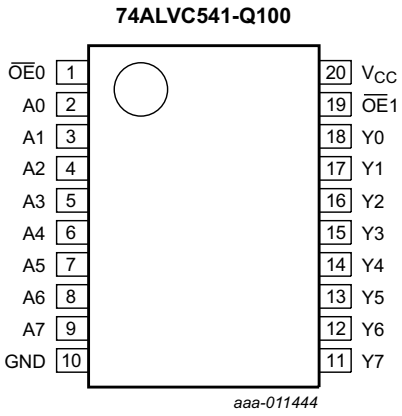
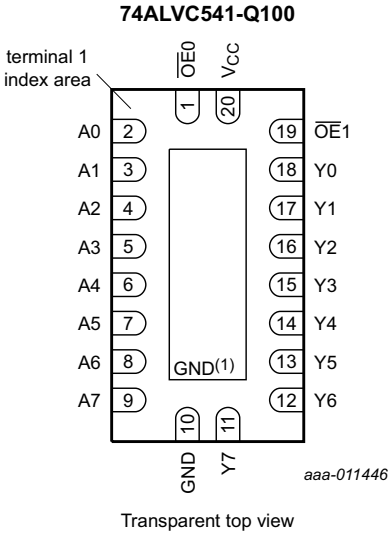


Fig 3. Pin configuration SO20, TSSOP20



Transparent top view

(1) This is not a supply pin. The substrate is attached to this pad using conductive die attach material. There is no electrical or mechanical requirement to solder this pad. However, if it is soldered, the solder land should remain floating or be connected to GND.

Fig 4. Pin configuration DHVQFN20

5.2 Pin description

Table 2. Pin description

Symbol	Pin	Description
$\overline{OE}0$	1	output enable input (active LOW)
A[0:7]	2, 3, 4, 5, 6, 7, 8, 9	data input
GND	10	ground (0 V)
Y[0:7]	18, 17, 16, 15, 14, 13, 12, 11	data output
$\overline{OE}1$	19	output enable input (active LOW)
V_{CC}	20	supply voltage

6. Functional description

Table 3. Functional table[1]

Control		Input	Output
$\overline{OE0}$	$\overline{OE1}$	An	Yn
L	L	L	L
L	L	H	H
X	H	X	Z
H	X	X	Z

[1] H = HIGH voltage level; L = LOW voltage level; X = don't care; Z = high-impedance OFF-state.

7. Limiting values

Table 4. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134). Voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	Min	Max	Unit
V_{CC}	supply voltage		−0.5	+4.6	V
V_I	input voltage		−0.5	+4.6	V
I_{IK}	input clamping current	$V_I < 0$ V [1]	−50	-	mA
I_{OK}	output clamping current	$V_O > V_{CC}$ or $V_O < 0$ V	-	±50	mA
V_O	output voltage	output HIGH or LOW state [2]	−0.5	V_{CC} + 0.5	V
		output 3-state [2]	−0.5	+4.6	V
		power-down mode, V_{CC} = 0 V [3]	−0.5	+4.6	V
I_O	output current	V_O = 0 V to V_{CC}	-	±50	mA
I_{CC}	supply current		-	100	mA
I_{GND}	ground current		−100	-	mA
T_{stg}	storage temperature		−65	+150	°C
P_{tot}	total power dissipation	T_{amb} = −40 °C to +85 °C			
	SO20 package	[4]	-	500	mW
	TSSOP20 package	[5]	-	500	mW
	DHVQFN20 package	[6]	-	500	mW

[1] The minimum input voltage ratings may be exceeded if the input current ratings are observed.

[2] The output voltage ratings may be exceeded if the output current ratings are observed.

[3] When V_{CC} = 0 V (Power-down mode), the output voltage can be 3.6 V in normal operation.

[4] P_{tot} derates linearly with 8 mW/K above 70 °C.

[5] P_{tot} derates linearly with 5.5 mW/K above 60 °C.

[6] P_{tot} derates linearly with 4.5 mW/K above 60 °C.

8. Recommended operating conditions

Table 5. Recommended operating conditions

Symbol	Parameter	Conditions	Min	Max	Unit
V_{CC}	supply voltage		1.65	3.6	V
V_I	input voltage		0	3.6	V
V_O	output voltage	output HIGH or LOW state	0	V_{CC}	V
		output 3-state	0	3.6	V
		power-down mode, V_{CC} = 0 V	0	3.6	V
T_{amb}	ambient temperature		−40	+85	°C
$\Delta t/\Delta V$	input transition rise and fall rate	V_{CC} = 1.65 V to 2.7 V	-	20	ns/V
		V_{CC} = 2.7 V to 3.6 V	-	10	ns/V

9. Static characteristics

Table 6. Static characteristics

At recommended operating conditions; voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	T_{amb} = –40 °C to +85 °C			Unit
			Min	Typ[1]	Max	
V_{IH}	HIGH-level input voltage	V_{CC} = 1.65 V to 1.95 V	0.65 × V_{CC}	-	-	V
		V_{CC} = 2.3 V to 2.7 V	1.7	-	-	V
		V_{CC} = 2.7 V to 3.6 V	2.0	-	-	V
V_{IL}	LOW-level input voltage	V_{CC} = 1.65 V to 1.95 V	-	-	0.35 × V_{CC}	V
		V_{CC} = 2.3 V to 2.7 V	-	-	0.7	V
		V_{CC} = 2.7 V to 3.6 V	-	-	0.8	V
V_{OH}	HIGH-level output voltage	V_I = V_{IH} or V_{IL}				
		I_O = 100 μA; V_{CC} = 1.65 V to 3.6 V	çXX–0.2	-	-	V
		I_O = 6 mA; V_{CC} = 1.65 V	1.25	-	-	V
		I_O = 12 mA; V_{CC} = 2.3 V	1.8	-	-	V
		I_O = 18 mA; V_{CC} = 2.3 V	1.7	-	-	V
		I_O = 12 mA; V_{CC} = 2.7 V	2.2	-	-	V
		I_O = 18 mA; V_{CC} = 3.0 V	2.4	-	-	V
		I_O = 24 mA; V_{CC} = 3.0 V	2.2	-	-	V
V_{OL}	LOW-level output voltage	V_I = V_{IH} or V_{IL}				
		I_O = –100 μA; V_{CC} = 1.65 V to 3.6 V	-	-	0.2	V
		I_O = –6 mA; V_{CC} = 1.65 V	-	-	0.3	V
		I_O = –12 mA; V_{CC} = 2.3 V	-	-	0.4	V
		I_O = –18 mA; V_{CC} = 2.3 V	-	-	0.6	V
		I_O = –12 mA; V_{CC} = 2.7 V	-	-	0.4	V
		I_O = –18 mA; V_{CC} = 3.0 V	-	-	0.4	V
		I_O = –24 mA; V_{CC} = 3.0 V	-	-	0.55	V
I_{OZ}	OFF-state output current	V_I = V_{IH} or V_{IL}; V_O = V_{CC} or GND; V_{CC} = 3.6 V	-	±0.1	±10.0	μA

Table 6. Static characteristics *...continued*

At recommended operating conditions; voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	T_{amb} = –40 °C to +85 °C			Unit
			Min	Typ[1]	Max	
I_I	input leakage current	$V_I = V_{CC}$ or GND; V_{CC} = 3.6 V	-	±0.1	±5.0	µA
I_{OFF}	power-off leakage current	V_I or V_O = 0 V to 3.6 V; V_{CC} = 0 V	-	±0.1	±10.0	µA
I_{CC}	supply current	$V_I = V_{CC}$ or GND; I_O = 0 A; V_{CC} = 3.6 V	-	0.2	10	µA
ΔI_{CC}	additional supply current	per input pin; V_{CC} = 3.0 V to 3.6 V; $V_I = V_{CC} - 0.6$ V; I_O = 0 A;	-	5	750	µA
C_I	input capacitance		-	3.5	-	pF

[1] All typical values are measured at V_{CC} = 3.3 V and T_{amb} = 25 °C.

10. Dynamic characteristics

Table 7. Dynamic characteristics

Voltages are referenced to GND (ground = 0 V); for test circuit, see Figure 7.

Symbol	Parameter	Conditions	T_{amb} = –40 °C to +85 °C			Unit
			Min	Typ[1]	Max	
t_{pd}	propagation delay	An to Yn; see Figure 5 [2]				
		V_{CC} = 1.65 V to 1.95 V	1.0	3.0	4.6	ns
		V_{CC} = 2.3 V to 2.7 V	1.0	2.2	3.3	ns
		V_{CC} = 27 V	1.0	2.5	3.3	ns
		V_{CC} = 3.0 V to 3.6 V	1.0	2.3	3.0	ns
t_{en}	enable time	$\overline{OE}$n to Yn; see Figure 6 [2]				
		V_{CC} = 1.65 V to 1.95 V	1.0	4.2	7.5	ns
		V_{CC} = 2.3 V to 2.7 V	1.0	3.3	5.4	ns
		V_{CC} = 27 V	1.0	3.7	5.8	ns
		V_{CC} = 3.0 V to 3.6 V	1.0	3.3	4.9	ns
t_{dis}	disable time	$\overline{OE}$n to Yn; see Figure 6 [2]				
		V_{CC} = 1.65 V to 1.95 V	1.0	4.8	7.5	ns
		V_{CC} = 2.3 V to 2.7 V	1.0	3.1	4.5	ns
		V_{CC} = 27 V	1.0	3.1	4.8	ns
		V_{CC} = 3.0 V to 3.6 V	1.0	2.9	4.6	ns

Table 7. Dynamic characteristics *...continued*

Voltages are referenced to GND (ground = 0 V); for test circuit, see Figure 7.

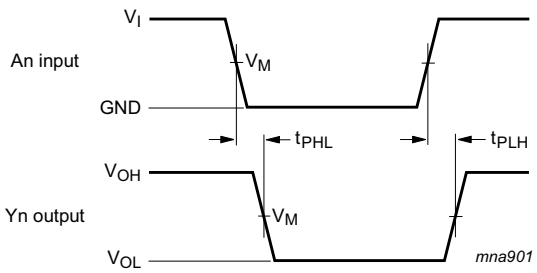
Symbol	Parameter	Conditions	T_{amb} = –40 °C to +85 °C			Unit
			Min	Typ[1]	Max	
C_{PD}	power dissipation capacitance	per buffer; V_I = GND to V_{CC}; V_{CC} = 3.3 V [3]				
		outputs enabled	-	25	-	pF
		outputs disabled	-	0	-	pF

[1] All typical values are measured at T_{amb} = 25 °C and V_{CC} = 1.8 V, 2.5 V, 2.7 V and 3.3 V.

[2] t_{pd} is the same as t_{PLH} and t_{PHL}.
t_{en} is the same as t_{PZL} and t_{PZH}.
t_{dis} is the same as t_{PLZ} and t_{PHZ}.

[3] C_{PD} is used to determine the dynamic power dissipation (P_D in μW).
$P_D = C_{PD} \times V_{CC}^2 \times f_i \times N + \Sigma(C_L \times V_{CC}^2 \times f_o)$ where:
f_i = input frequency in MHz;
f_o = output frequency in MHz;
C_L = output load capacitance in pF;
V_{CC} = supply voltage in V;
N = number of inputs switching;
$\Sigma(C_L \times V_{CC}^2 \times f_o)$ = sum of the outputs.

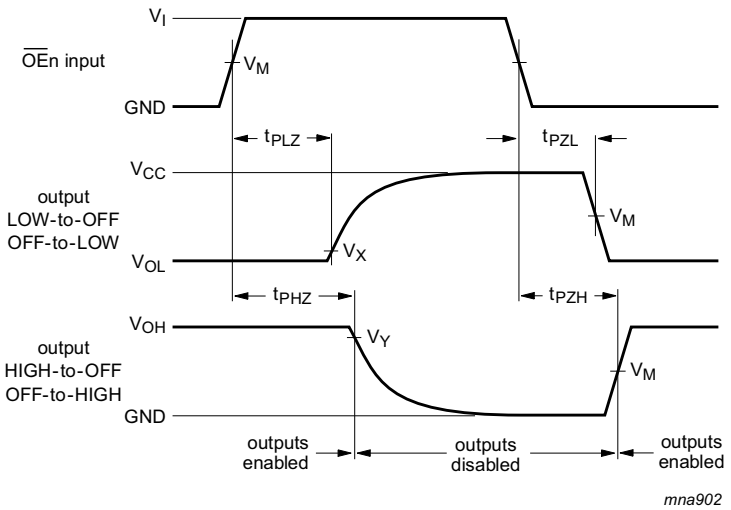
11. Waveforms



Measurement points are given in Table 8.

V_{OL} and V_{OH} are typical voltage output levels that occur with the output load.

Fig 5. Propagation delay input (An) to output (Yn)



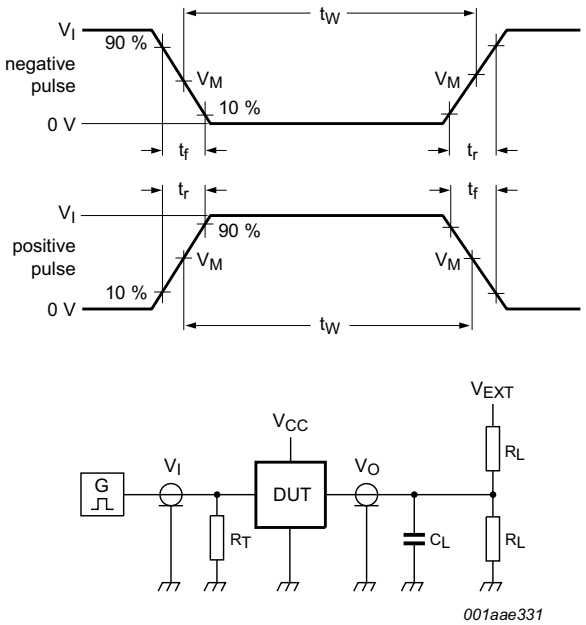
Measurement points are given in Table 8.

V_{OL} and V_{OH} are typical voltage output levels that occur with the output load.

Fig 6. Enable and disable times

Table 8. Measurement points

Supply voltage	Input		Output		
V_{CC}	V_I	V_M	V_M	V_X	V_Y
1.65 V to 1.65 V	V_{CC}	$0.5 \times V_{CC}$	$0.5 \times V_{CC}$	V_{OL} + 0.15 V	V_{OH} − 0.15 V
2.3 V to 2.7 V	V_{CC}	$0.5 \times V_{CC}$	$0.5 \times V_{CC}$	V_{OL} + 0.15 V	V_{OH} − 0.15 V
2.7 V	2.7 V	1.5 V	1.5 V	V_{OL} + 0.3 V	V_{OH} − 0.3 V
3.0 V to 3.6 V	2.7 V	1.5 V	1.5 V	V_{OL} + 0.3 V	V_{OH} − 0.3 V



Test data is given in Table 9.

Definitions test circuit:

R_T = Termination resistance should be equal to output impedance Z_o of the pulse generator

C_L = Load capacitance including jig and probe capacitance

R_L = Load resistor

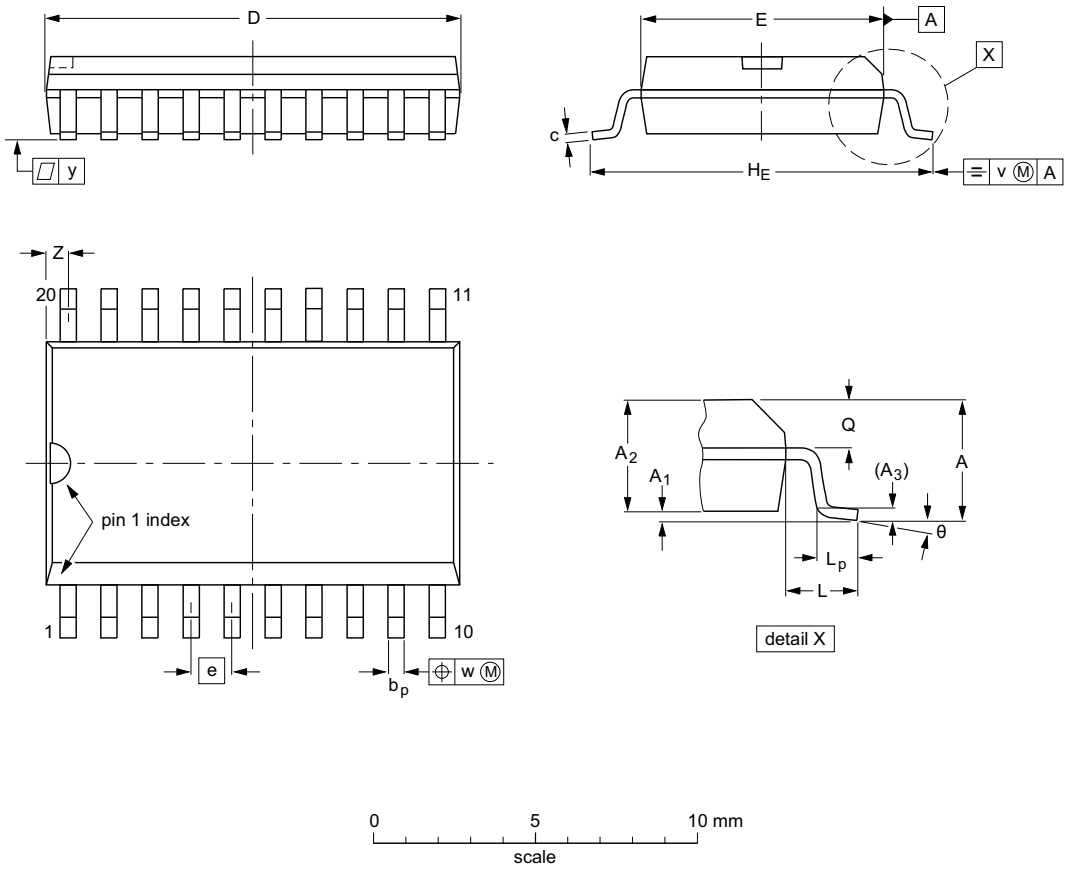
Fig 7. Test circuit for measuring switching times

Table 9. Test data

Supply voltage	Input		Load		V_{EXT}		
V_{CC}	V_I	t_r, t_f	C_L	R_L	t_{PLH}, t_{PHL}	t_{PLZ}, t_{PZL}	t_{PHZ}, t_{PZH}
1.65 V to 1.95 V	V_{CC}	≤ 2.0 ns	30 pF	1 kΩ	open	2 × V_{CC}	GND
2.3 V to 2.7 V	V_{CC}	≤ 2.0 ns	30 pF	500 Ω	open	2 × V_{CC}	GND
2.7 V	2.7 V	≤ 2.5 ns	50 pF	500 Ω	open	6	GND
3.0 V to 3.6 V	2.7 V	≤ 2.5 ns	50 pF	500 Ω	open	6	GND

12. Package outline

SO20: plastic small outline package; 20 leads; body width 7.5 mm **SOT163-1**



DIMENSIONS (inch dimensions are derived from the original mm dimensions)

UNIT	A max.	A_1	A_2	A_3	b_p	c	D (1)	E (1)	e	H_E	L	L_p	Q	v	w	y	Z (1)	θ
mm	2.65	0.3 0.1	2.45 2.25	0.25	0.49 0.36	0.32 0.23	13.0 12.6	7.6 7.4	1.27	10.65 10.00	1.4	1.1 0.4	1.1 1.0	0.25	0.25	0.1	0.9 0.4	8° 0°
inches	0.1	0.012 0.004	0.096 0.089	0.01	0.019 0.014	0.013 0.009	0.51 0.49	0.30 0.29	0.05	0.419 0.394	0.055	0.043 0.016	0.043 0.039	0.01	0.01	0.004	0.035 0.016	

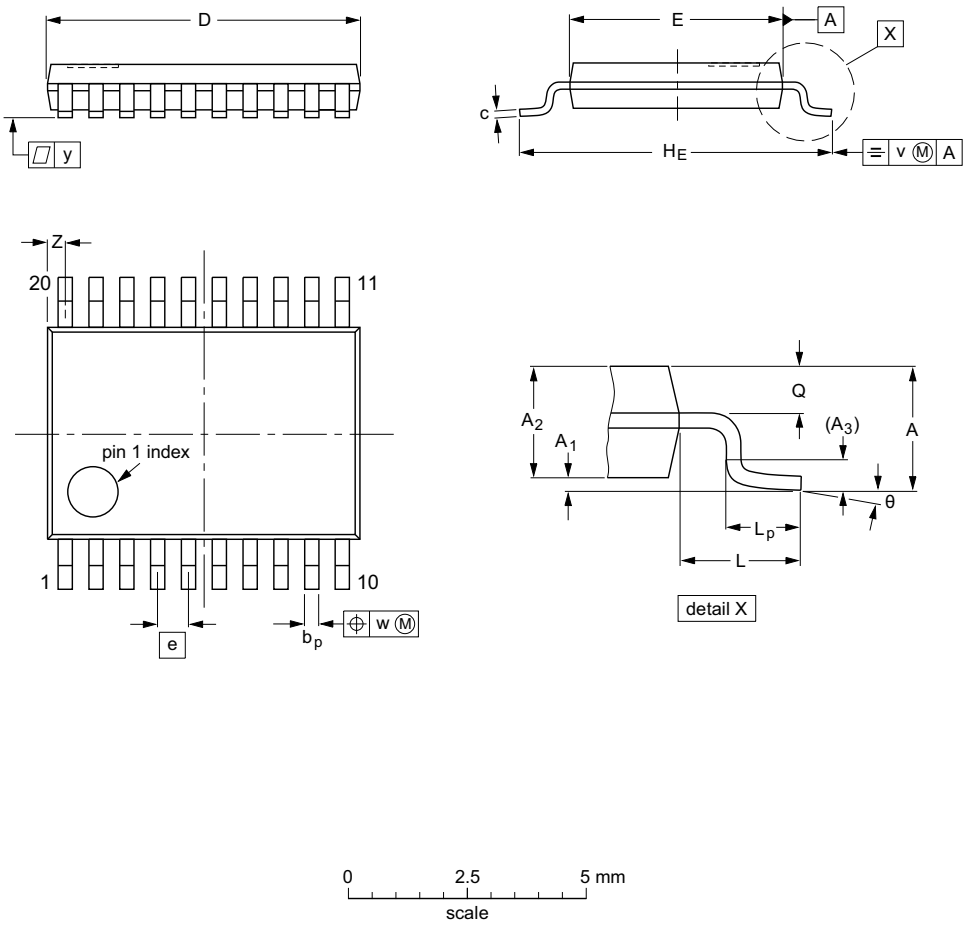
Note

1. Plastic or metal protrusions of 0.15 mm (0.006 inch) maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT163-1	075E04	MS-013				~~99-12-27~~ 03-02-19

Fig 8. Package outline SOT163-1 (SO20)

TSSOP20: plastic thin shrink small outline package; 20 leads; body width 4.4 mm **SOT360-1**



DIMENSIONS (mm are the original dimensions)

UNIT	A max.	A_1	A_2	A_3	b_p	c	D (1)	E (2)	e	H_E	L	L_p	Q	v	w	y	Z (1)	θ
mm	1.1	0.15 0.05	0.95 0.80	0.25	0.30 0.19	0.2 0.1	6.6 6.4	4.5 4.3	0.65	6.6 6.2	1	0.75 0.50	0.4 0.3	0.2	0.13	0.1	0.5 0.2	8° 0°

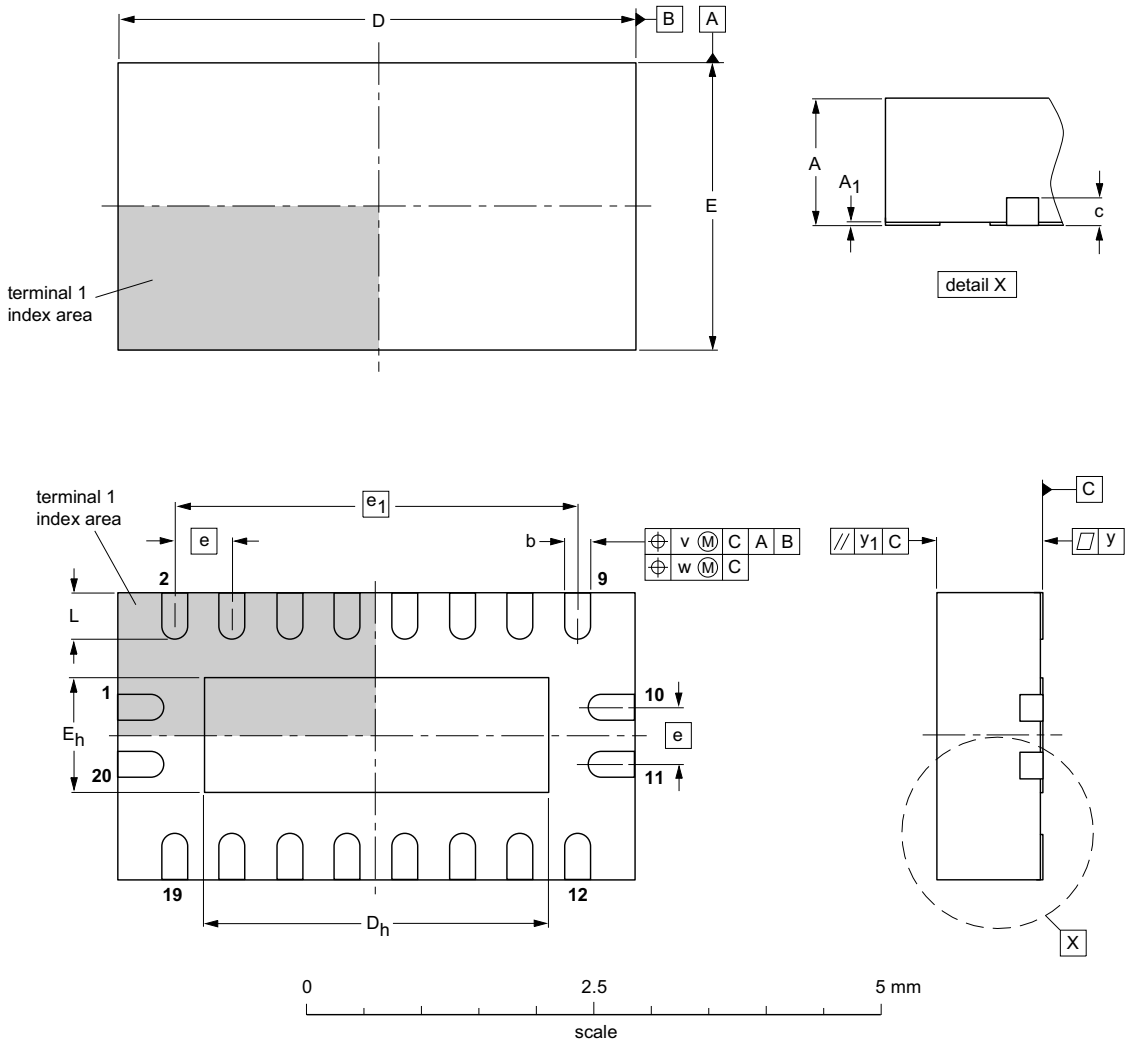
Notes

1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.
2. Plastic interlead protrusions of 0.25 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT360-1		MO-153				~~99-12-27~~ 03-02-19

Fig 9. Package outline SOT360-1 (TSSOP20)

DHVQFN20: plastic dual in-line compatible thermal enhanced very thin quad flat package; no leads; 20 terminals; body 2.5 x 4.5 x 0.85 mm **SOT764-1**



DIMENSIONS (mm are the original dimensions)

UNIT	$A^{(1)}$ max.	A_1	b	c	$D^{(1)}$	D_h	$E^{(1)}$	E_h	e	e_1	L	v	w	y	y_1
mm	1	0.05 0.00	0.30 0.18	0.2	4.6 4.4	3.15 2.85	2.6 2.4	1.15 0.85	0.5	3.5	0.5 0.3	0.1	0.05	0.05	0.1

Note

1. Plastic or metal protrusions of 0.075 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT764-1	- - -	MO-241	- - -			~~02-10-17~~ 03-01-27

Fig 10. Package outline SOT764-1 (DHVQFN20)

13. Abbreviations

Table 10. Abbreviations

Acronym	Description
CDM	Charged Device Model
DUT	Device Under Test
ESD	ElectroStatic Discharge
HBM	Human Body Model
MIL	Military
MM	Machine Model
TTL	Transistor-Transistor Logic

14. Revision history

Table 11. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
74ALVC541_Q100 v.1	20140519	Product data sheet	-	-

15. Legal information

15.1 Data sheet status

Document status[1][2]	Product status[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

[3] The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the Internet at URL http://www.nxp.com.

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